

Examiner: *GJ*

AN 1998:767861 HCAPLUS  
DN 130:55715  
TI Lead-free **tin** alloy solders for printed circuit board showing  
excellent melting property, wettability and mechanical strength  
IN Takeda, Naoko; Hanyu, Kazutaka  
PA Sony Corp., Japan  
SO Jpn. Kokai Tokkyo Koho, 6 pp.  
CODEN: JKXXAF  
DT Patent  
LA Japanese  
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 10314980	A2	19981202	JP 1997-124445	19970514
AB	The alloys are <b>Sn</b> alloys contg. Bi 1.0-12.0, <b>Ag</b> 0.5-6.0, <b>Cu</b> 0.1-3.0, and In 0.5-10 wt.%. 				